

1.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER
Features

- Guard Ring Die Construction for Transient Protection
- Very Low Forward Voltage Drop
- **Lead, Halogen and Antimony Free, RoHS Compliant "Green" Device (Notes 3 and 4)**

Mechanical Data

- Case: SOD-123
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe) Solderable per MIL-STD-202, Method 208
- Polarity: Cathode Band
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.01 grams (approximate)



Top View

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	30	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_R		
RMS Reverse Voltage	$V_{R(RMS)}$	21	V
Average Forward Current (See Figure 6)	$I_{F(AV)}$	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	12	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 2)	P_D	450	mW
Typical Thermal Resistance Junction to Ambient (Note 2)	$R_{\theta JA}$	222	$^\circ\text{C}/\text{W}$
Operating Temperature Range (See Figure 7)	T_J	-55 to +125	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 to +150	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 1)	$V_{(BR)R}$	30	—	—	V	$I_R = 1.5\text{mA}$
Forward Voltage	V_F	—	0.25	—	V	$I_F = 0.1\text{A}$
		—	0.35	0.37		$I_F = 0.7\text{A}$
		—	0.38	0.42		$I_F = 1.0\text{A}$
Leakage Current (Note 1)	I_R	—	0.15	1.0	mA	$V_R = 30\text{V}, T_A = 25^\circ\text{C}$
Total Capacitance	C_T	—	40	—	pF	$V_R = 10\text{V}, f = 1.0\text{MHz}$

- Notes:
1. Short duration pulse test used to minimize self-heating effect.
 2. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 3. No purposefully added lead. Halogen and Antimony Free.
 4. Product manufactured with Data Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb_2O_3 Fire Retardants.

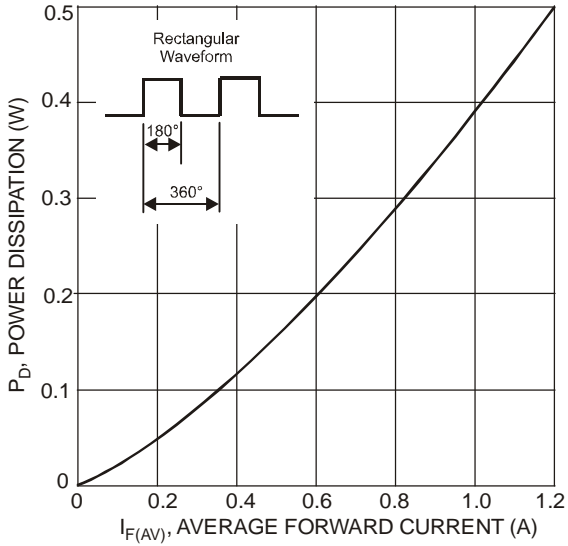


Fig. 1 Forward Power Dissipation

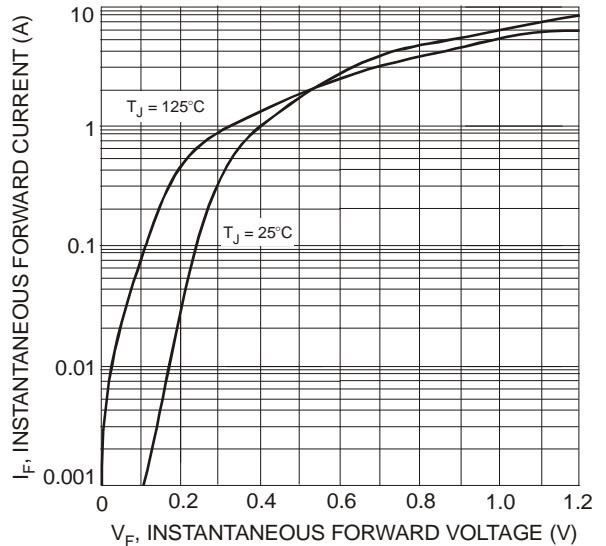


Fig. 2 Typical Forward Characteristics

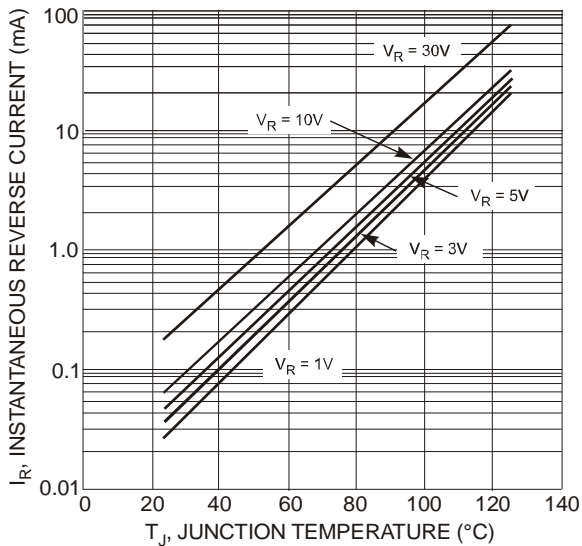


Fig. 3 Typical Pulsed Reverse Characteristics

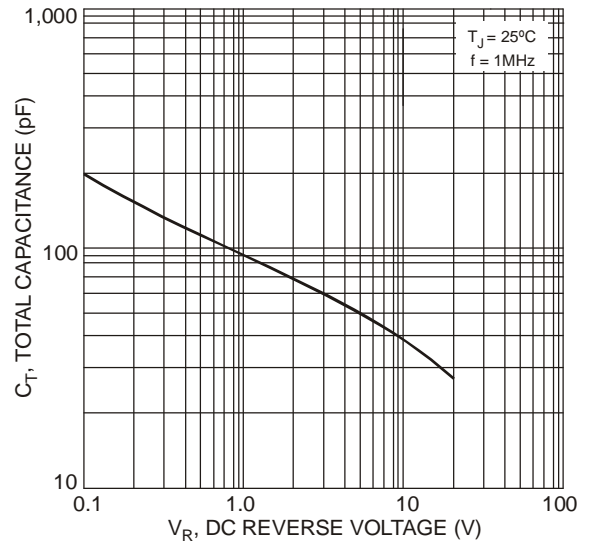


Fig. 4 Total Capacitance vs. Reverse Voltage

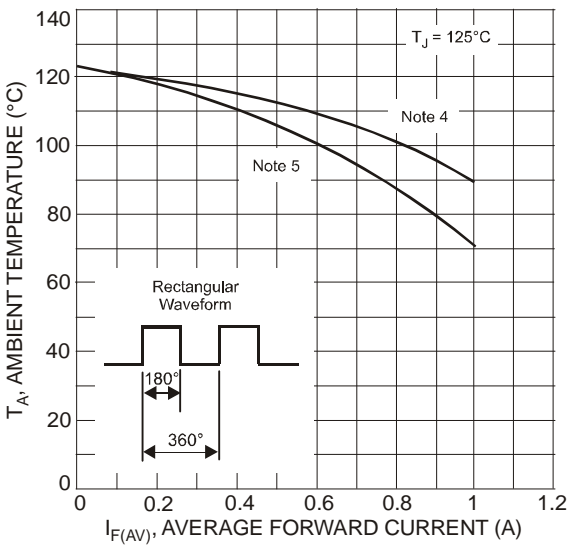


Fig. 5 Forward Current Derating Curve

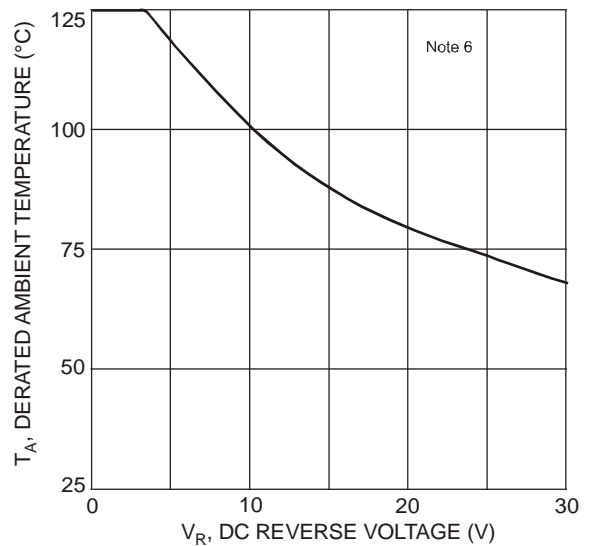


Fig. 6 Operating Temperature Derating

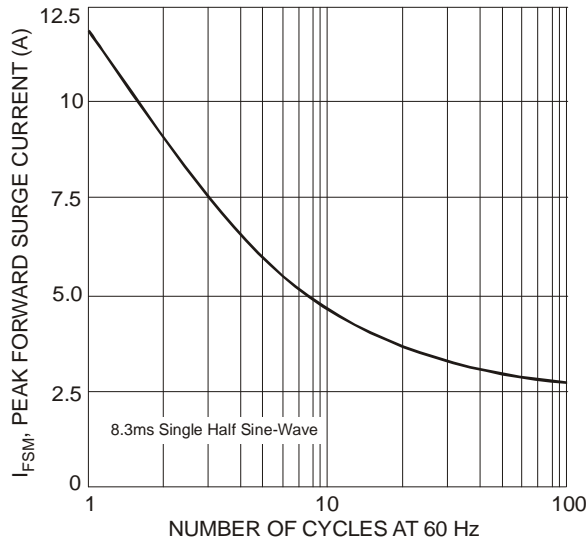


Fig. 7 Maximum Non-Repetitive Peak Forward Surge Current

- Notes:
5. Device mounted on GETEK substrate, 2"x2", 2 oz. copper, double-sided, cathode pad dimensions 0.75" x 1.0", anode pad dimensions 0.25" x 1.0".
 6. Device mounted on FR-4 substrate, 2"x2", 2 oz. copper, single-sided, pad layout as per Diodes Inc. suggested pad layout document AP02001 which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
 7. $R_{\theta JA}$ estimated to be approximately 220 °C/W.

Ordering Information (Note 8)

Part Number	Case	Packaging
B130LAW-7-F	SOD-123	3000/Tape & Reel

Notes: 8. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



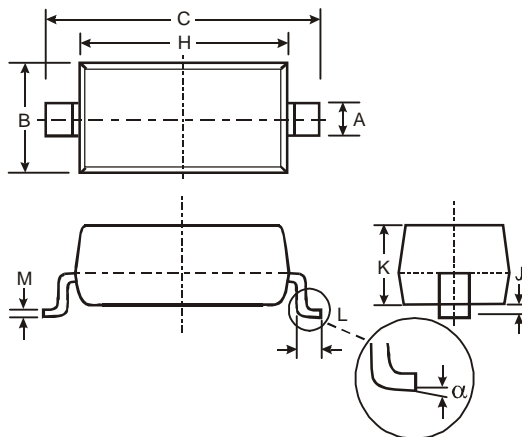
SX = Product Type Marking Code
 YM = Date Code Marking
 Y = Year ex: T = 2006
 M = Month (ex: 9 = September)

Date Code Key

Year	2006	2007	2008	2009	2010	2011	2012
Code	T	U	V	W	X	Y	Z

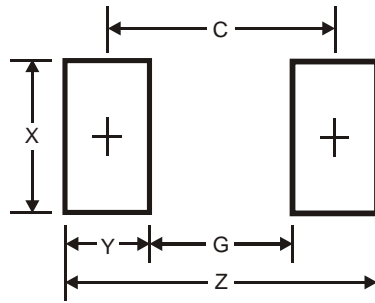
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SOD-123		
Dim	Min	Max
A	0.55 Typ	
B	1.40	1.70
C	3.55	3.85
H	2.55	2.85
J	0.00	0.10
K	1.00	1.35
L	0.25	0.40
M	0.10	0.15
α	0	8°
All Dimensions in mm		

Suggested Pad Layout



Dimensions	Value (in mm)
Z	4.9
G	2.5
X	0.7
Y	1.2
C	3.7

IMPORTANT NOTICE

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to any product herein. Diodes Incorporated does not assume any liability arising out of the application or use of any product described herein; neither does it convey any license under its patent rights, nor the rights of others. The user of products in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on our website, harmless against all damages.

LIFE SUPPORT

Diodes Incorporated products are not authorized for use as critical components in life support devices or systems without the expressed written approval of the President of Diodes Incorporated.

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Diodes Incorporated:](#)

[B130LAW-7-F](#)